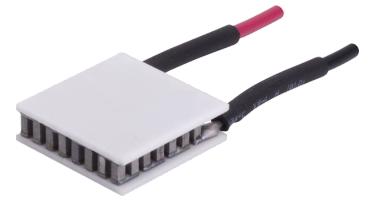
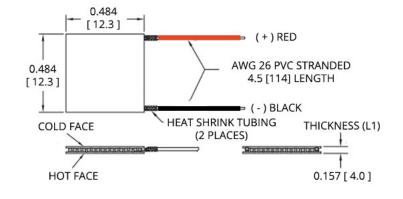
Ceramic Plate Series Thermoelectric Cooler

The CP10-31-08-L1-RT-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 5.1 Watts when $\Delta T = 0$ and a maximum ΔT of 70.5 °C at Qc = 0.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant
- Applications
- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision



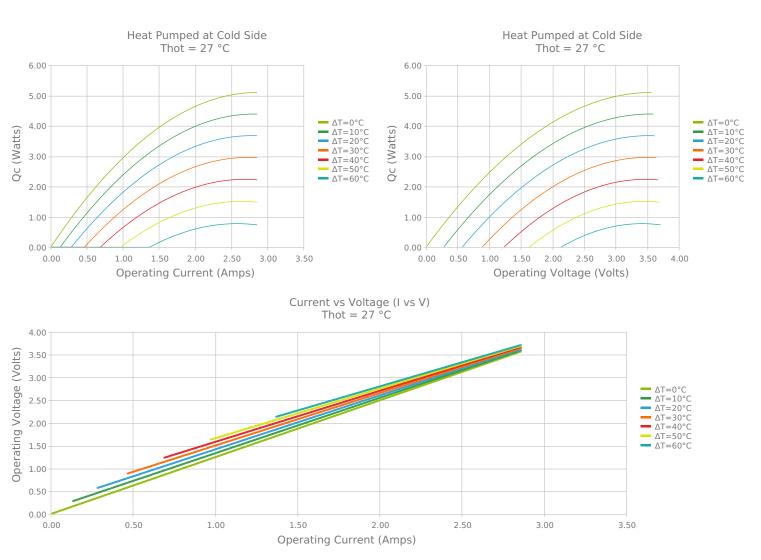


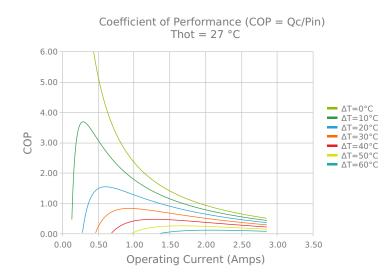
Ceramic Material: Alumina (Al₂O₃) Solder Construction: 138°C, Bismuth Tin (BiSn)

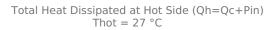
INCHES [MM]

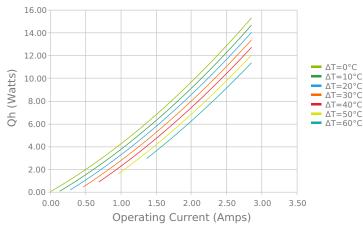
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

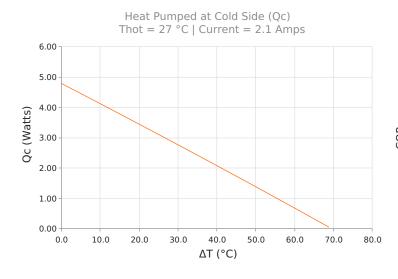
ELECTRICAL AND THERMAL PERFORMANCE

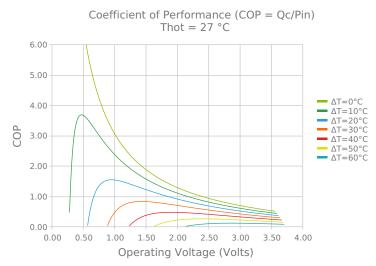




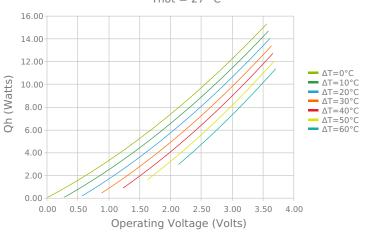




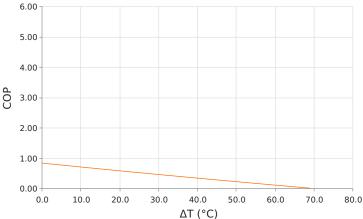




Total Heat Dissipated at Hot Side (Qh=Qc+Pin) Thot = 27 $^{\circ}C$



Coefficient of Performance (COP = Qc/Pin) Thot = $27 \degree C$ | Current = 2.1 Amps



SPECIFICATIONS*

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
$Qcmax (\Delta T = 0)$	5.1 Watts	5.3 Watts	5.5 Watts
$\Delta Tmax (Qc = 0)$	70.5°C	73.5°C	78.8°C
lmax (I @ ΔTmax)	2.5 Amps	2.5 Amps	2.5 Amps
Vmax (V @ ΔTmax)	3.4 Volts	3.5 Volts	3.8 Volts
Module Resistance	1.25 Ohms	1.30 Ohms	1.40 Ohms
Max Operating Temperature	80 °C		
Weight	4.0 gram(s)		

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	3.988 ±0.025 mm 0.157 ± 0.001 in	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
RT	RTV	White	-60 to 204°C	Non-corrosive, silicone adhesive

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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Date: 04/24/2020